

SOT918-1

plastic thin fine-pitch ball grid array package; 48 balls; body
5 x 5 x 0.8 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA48
Package type industry code	TFBGA48
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-195
Mounting method type	S (surface mount)
Issue date	13-10-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
A	seated height	[tbd]	-	1.15	1.15	mm
A ₂	package height	0.75	-	0.8	0.9	mm
n ₂	actual quantity of termination	-	-	48	-	



2. Package outline

TFBGA48: plastic thin fine-pitch ball grid array package; 48 balls; body 5 x 5 x 0.8 mm SOT918-1

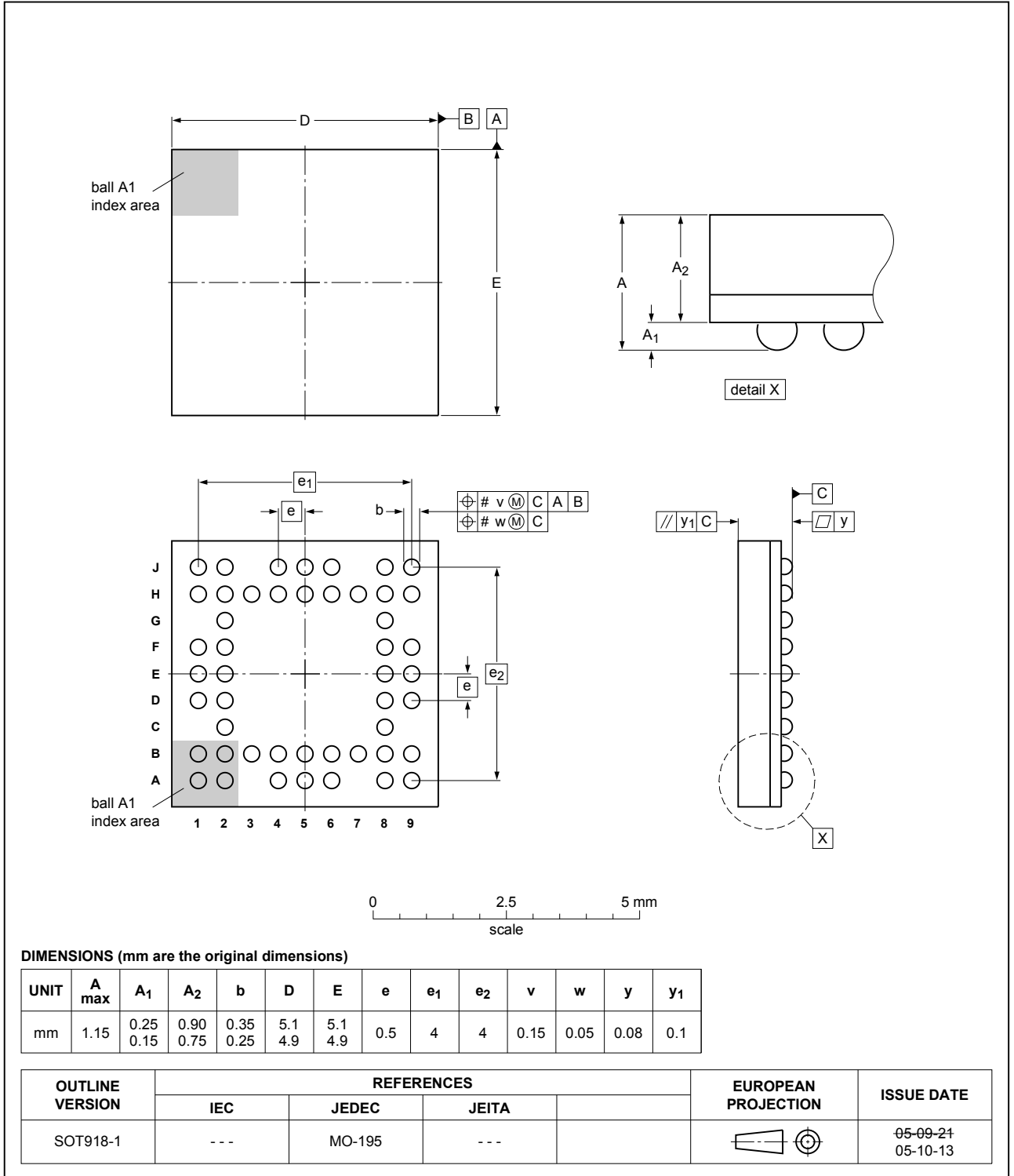


Fig. 1. Package outline TFBGA48 (SOT918-1)

3. Soldering

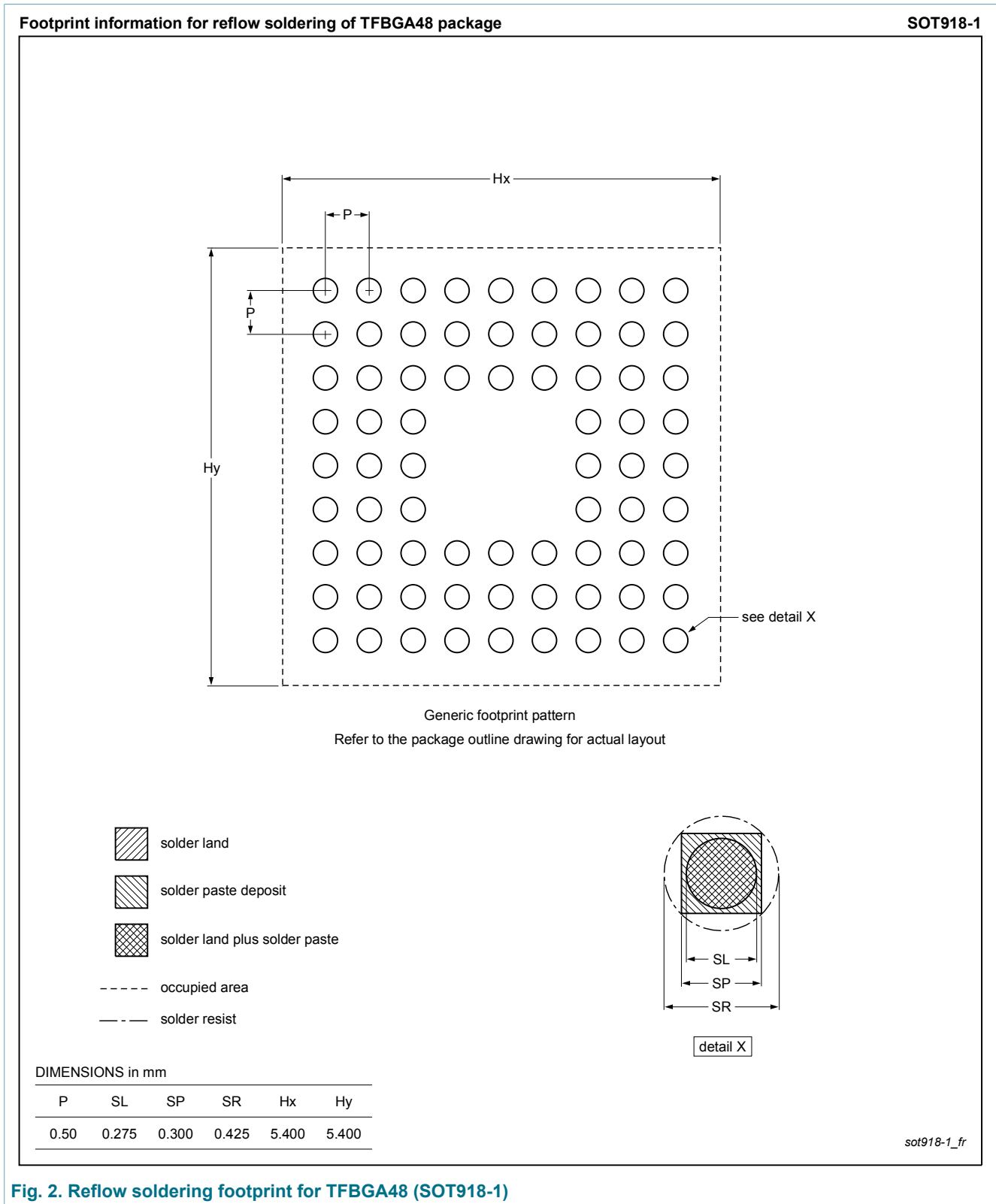


Fig. 2. Reflow soldering footprint for TFBGA48 (SOT918-1)

4. Legal information

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